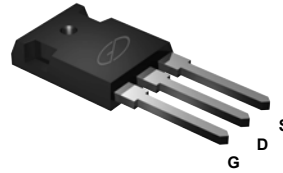
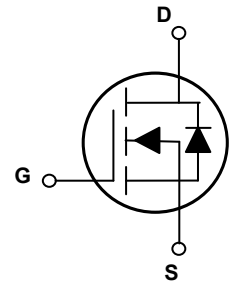


Main Product Characteristics

| | |
|---------------|----------------------|
| $V_{(BR)DSS}$ | 150V |
| $R_{DS(ON)}$ | 4.8m Ω (Typ.) |
| I_D | 175A |



TO-247



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSGA6R015 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|--|------------------|-------------|------|
| Drain-Source Voltage | V _{DS} | 150 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Drain Current-Continuous, at Steady-State, (T _C =25°C) ¹ | I _D | 175 | A |
| Drain Current-Continuous, at Steady-State, (T _C =100°C) | | 124 | |
| Drain Current-Pulsed ² | I _{DM} | 690 | A |
| Single Pulse Avalanche Energy ³ | E _{AS} | 803 | mJ |
| Power Dissipation (T _A =25°C) | P _D | 500 | W |
| Linear Derating Factor (T _A =25°C) | | 3.33 | W/°C |
| Junction-to-Ambient (PCB Mounted, Steady-State) ⁴ | R _{θJA} | 62 | °C/W |
| Thermal Resistance, Junction-to-Case | R _{θJC} | 0.3 | °C/W |
| Operating Junction Temperature Range | T _J | -55 To +175 | °C |
| Storage Temperature Range | T _{STG} | -55 To +175 | °C |

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|--------------|--|------|-------|-----------|------------|
| On / Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 150 | - | - | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{DS}=150V, V_{GS}=0V$ | - | - | 1 | μA |
| | | $T_J=125^\circ\text{C}$ | - | - | 50 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=100A$ | - | 4.8 | 6.0 | m Ω |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS}=V_{DS}, I_D=250\mu A$ | 2.1 | 3 | 3.9 | V |
| Dynamic and Switching Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{DS}=120V, I_D=100A, V_{GS}=10V$ | - | 81 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 29 | - | |
| Gate-Drain ("Miller") Charge | Q_{gd} | | - | 15 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DS}=75V, R_{GEN}=2.5\Omega, V_{GS}=10V, I_D=80A$ | - | 16.5 | - | nS |
| Rise Time | t_r | | - | 106.3 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 60.6 | - | |
| Fall Time | t_f | | - | 104.6 | - | |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$ | - | 5400 | - | pF |
| Output Capacitance | C_{oss} | | - | 3300 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 80 | - | |
| Gate Resistance | R_g | $F=1\text{MHz}$ | - | 4.3 | - | Ω |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Continuous Source Current (Body Diode) | I_S | MOSFET symbol showing the integral reverse p-n junction diode. | - | - | 175 | A |
| Pulsed Source Current (Body Diode) | I_{SM} | | - | - | 690 | A |
| Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_S=80A$ | - | 1 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_J=25^\circ\text{C}, I_F=80A, di/dt=100A/\mu s$ | - | 110 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 0.36 | - | μC |

Note:

1. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. $L=0.3\text{mH}, V_{DD}=50V, R_G=25\Omega, T_J=25^\circ\text{C}$.
4. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062inch.

Typical Electrical and Thermal Characteristic Curves

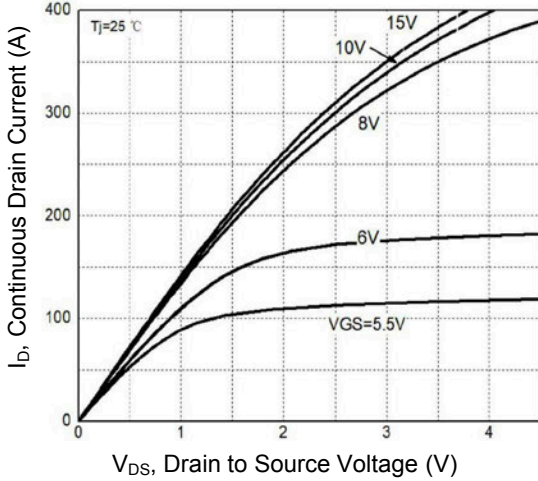


Figure 1. Typical Output Characteristics

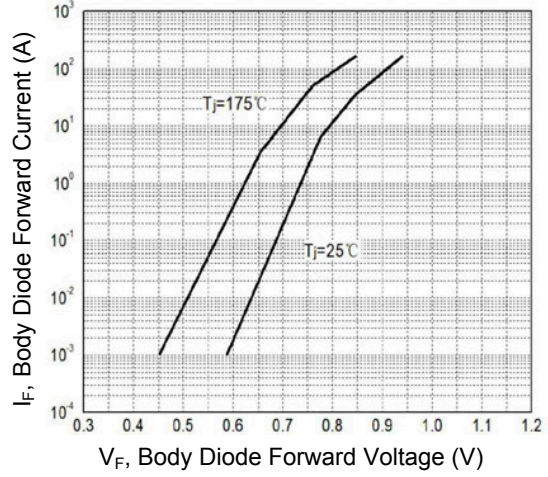


Figure 2. Body Diode Characteristics

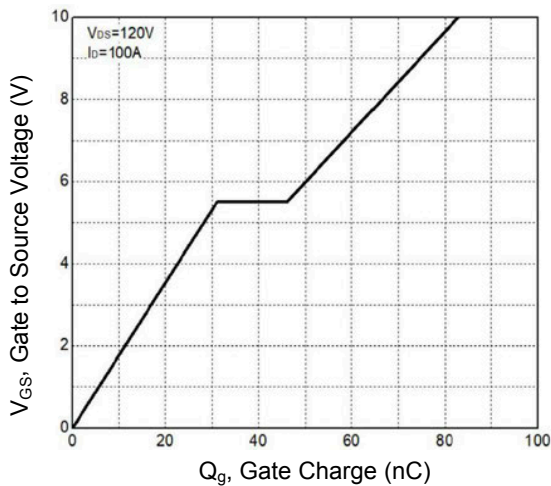


Figure 3. Gate Charge Characteristics

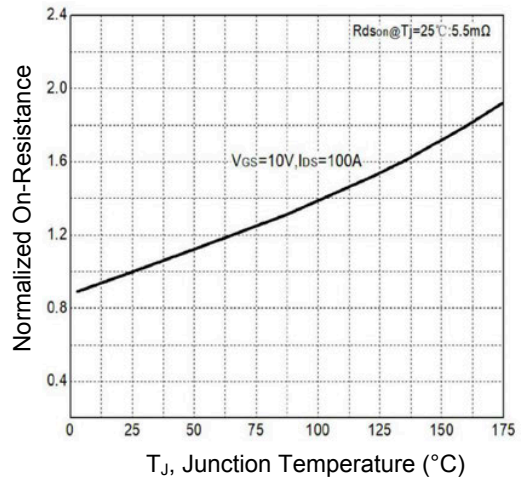


Figure 4. Normalized $R_{DS(ON)}$ vs. T_J

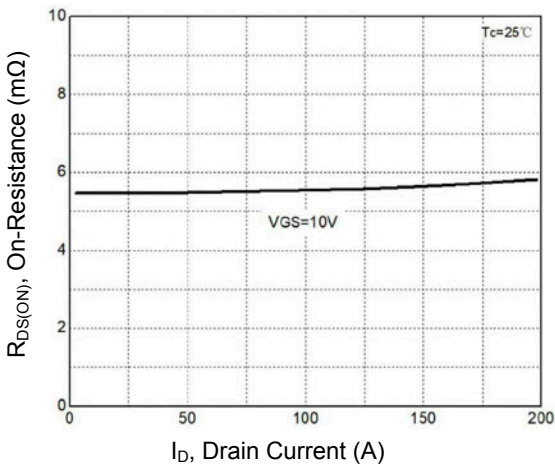


Figure 5. $R_{DS(ON)}$ vs. Drain Current

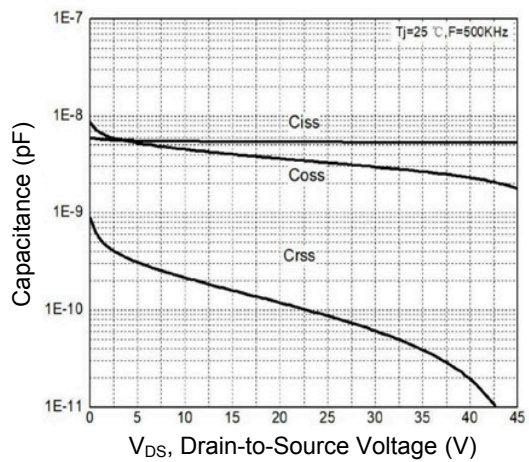


Figure 6. Capacitance Characteristics

Typical Electrical and Thermal Characteristic Curves

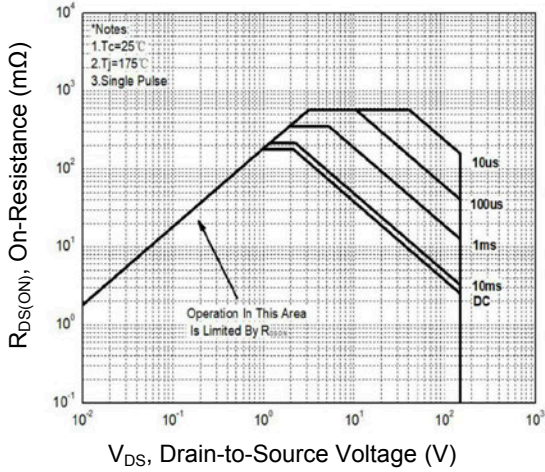


Figure 7. Safe Operation Area

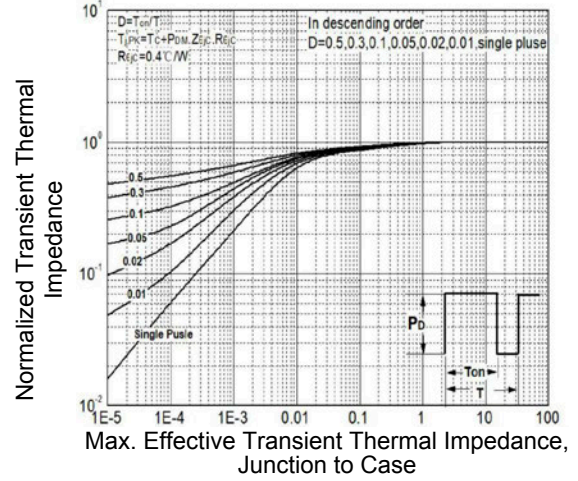
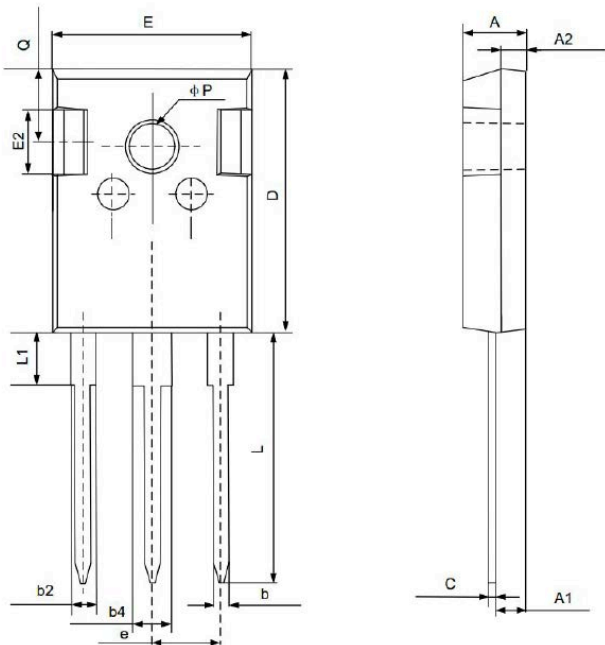


Figure 8. Thermal Transient Impedance

Package Outline Dimensions (TO-247)



| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 4.800 | 5.200 | 0.189 | 0.205 |
| A1 | 2.210 | 2.590 | 0.087 | 0.102 |
| A2 | 1.850 | 2.150 | 0.073 | 0.085 |
| b | 1.110 | 1.360 | 0.044 | 0.054 |
| b2 | 1.910 | 2.250 | 0.075 | 0.089 |
| b4 | 2.910 | 3.250 | 0.115 | 0.128 |
| c | 0.510 | 0.750 | 0.020 | 0.030 |
| D | 20.800 | 21.300 | 0.819 | 0.839 |
| E | 15.500 | 16.100 | 0.610 | 0.634 |
| E2 | 4.400 | 5.200 | 0.173 | 0.205 |
| e | 5.440 BSC | | 0.214 BSC | |
| L | 19.720 | 20.220 | 0.776 | 0.796 |
| L1 | - | 4.300 | - | 0.169 |
| Q | 5.600 | 6.000 | 0.220 | 0.236 |
| P | 3.400 | 3.800 | 0.134 | 0.150 |